NEC

MOS FIELD EFFECT POWER TRANSISTOR

μPA1700

SWITCHING
N-CHANNEL POWER MOS FET
INDUSTRIAL USE

DESCRIPTION

This product is N-Channel MOS Field Effect Transistor designed for DC/DC converter and power management applications of note book computers.

FEATURES

- Low On-Resistance
  $R_{DS(on)1}$ = 27 mΩ Typ. (V_{GS} = 10 V, I_D = 3.5 A)
  $R_{DS(on)2}$ = 50 mΩ Typ. (V_{GS} = 4 V, I_D = 3.5 A)
- Low C_{iss} C_{iss} = 850 pF Typ.
- Built-in G-S Protection Diode
- Small and Surface Mount Package
  (Power SOP8)

ORDERING INFORMATION

PART NUMBER	PACKAGE
μPA1700G	Power SOP8

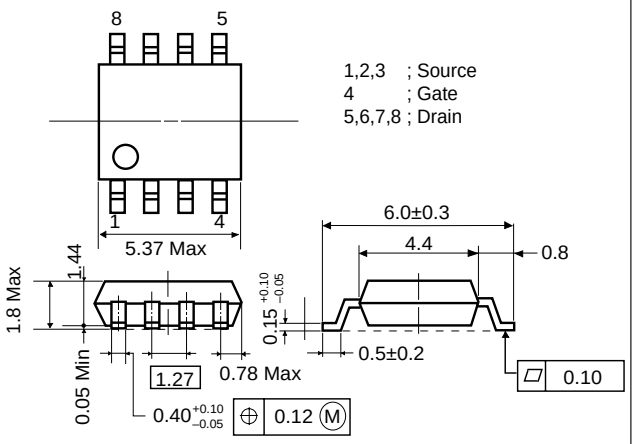
ABSOLUTE MAXIMUM RATINGS (T_A = 25 °C)

Drain to Source Voltage	V_{DSS}	30	V
Gate to Source Voltage	V_{GDS}	±20	V
Drain Current (DC)	$I_{D(DC)}$	±7.0	A
Drain Current (pulse)*	$I_{D(pulse)}$	±28	A
Total Power Dissipation (T_A = 25 °C)**	P_T	2.0	W
Channel Temperature	T_{CH}	150	°C
Storage Temperature	T_{stg}	–55 to +150	°C

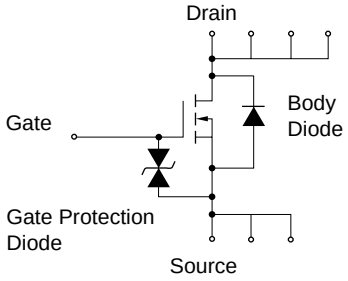
* PW ≤ 10 μs, Duty Cycle ≤ 1 %

** Mounted on ceramic substate of 1200 $mm^2 \times 0.7$ mm

PACKAGE DIMENSIONS
(in millimeter)



EQUIVALENT CIRCUIT



To keep good radiate condition,
It is recommended that all pins
are soldering to print board.

The diode connected between the gate and source of the transistor serves as a protector against ESD. When this device is actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

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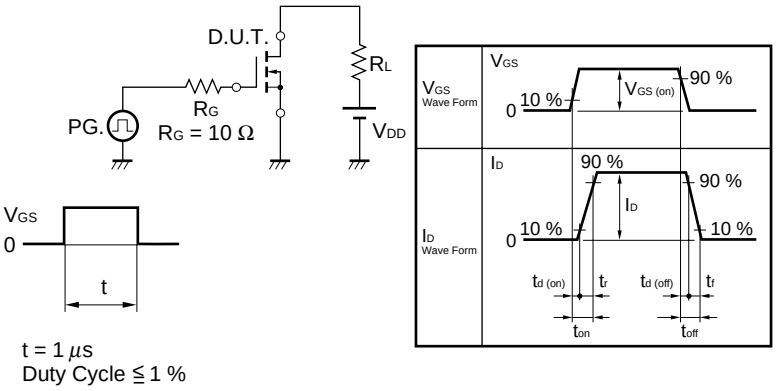
ELECTRICAL CHARACTERISTICS (T_A = 25 °C)

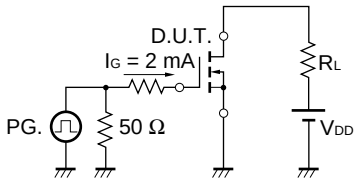
CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Drain to Source On-state Resistance	$R_{DS(on)1}$	V_{GS} = 10 V, I_D = 3.5 A		20	27	mΩ
	$R_{DS(on)2}$	V_{GS} = 4 V, I_D = 3.5 A		33	50	mΩ
Gate to Source Cutoff Voltage	$V_{GS(off)}$	V_{DS} = 10 V, I_D = 1 mA	1.0	1.6	2.0	V
Forward Transfer Admittance	$\|y_{fs}\|$	V_{DS} = 10 V, I_D = 3.5 A	5.0			S
Drain Leakage Current	I_{DSS}	V_{DS} = 30 V, V_{GS} = 0			10	μA
Gate to Source Leakage Current	I_{GSS}	V_{GS} = ±20 V, V_{DS} = 0			±10	μA
Input Capacitance	C_{iss}	V_{DS} = 10 V		850		pF
Output Capacitance	C_{oss}	V_{GS} = 0		550		pF
Reverse Transfer Capacitance	C_{rss}	f = 1 MHz		270		pF
Turn-On Delay Time	$t_{d(on)}$	I_D = 3.5 A		20		ns
Rise Time	t_r	$V_{GS(on)}$ = 10 V		105		ns
Turn-Off Delay Time	$t_{d(off)}$	V_{DD} = 15 V		90		ns
Fall Time	t_f	R_G = 10 Ω		60		ns
Total Gate Charge	Q_G	I_D = 7.0 A		33		nC
Gate to Source Charge	Q_{GS}	V_{DD} = 24 V		2.4		nC
Gate to Drain Charge	Q_{GD}	V_{GS} = 10 V		13		nC
Body Diode Forward Voltage	$V_{F(S-D)}$	I_F = 7.0 A, V_{GS} = 0		0.84		V
Reverse Recovery Time	t_{rr}	I_F = 7.0 A, V_{GS} = 0		60		ns
Reverse Recovery Charge	Q_{rr}	di/dt = 100 A/μs		90		nC

Test Circuit 1 Switching Time



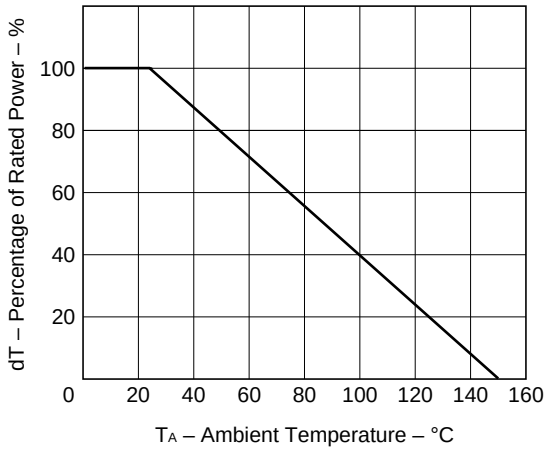
t = 1 μs
Duty Cycle ≦ 1 %

Test Circuit 2 Gate Charge

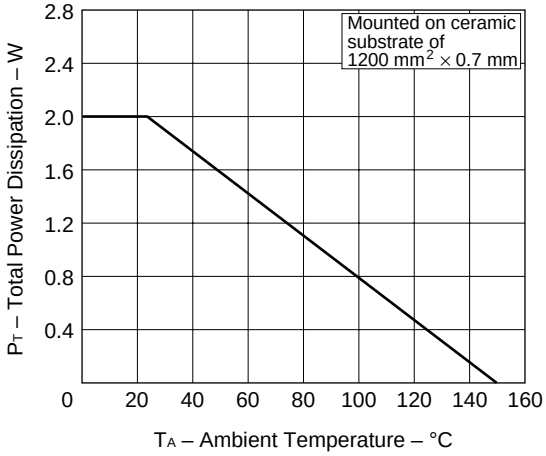


TYPICAL CHARACTERISTICS (T_A = 25 °C)

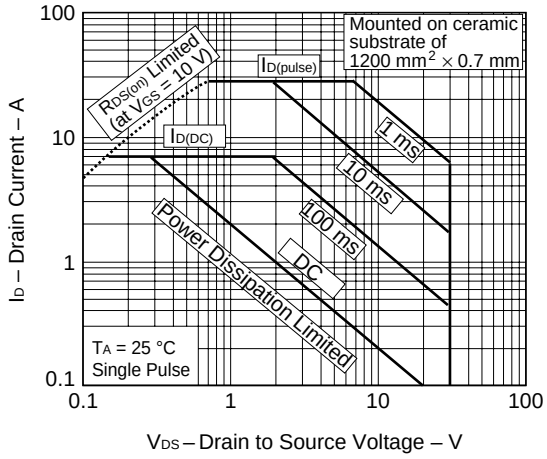
DERATING FACTOR OF FORWARD BIAS SAFE OPERATING AREA



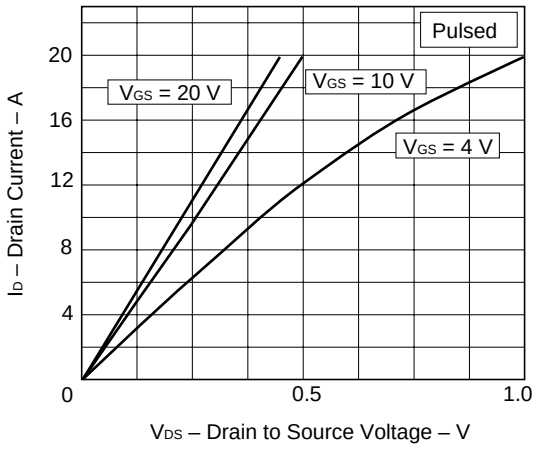
TOTAL POWER DISSIPATION vs. AMBIENT TEMPERATURE



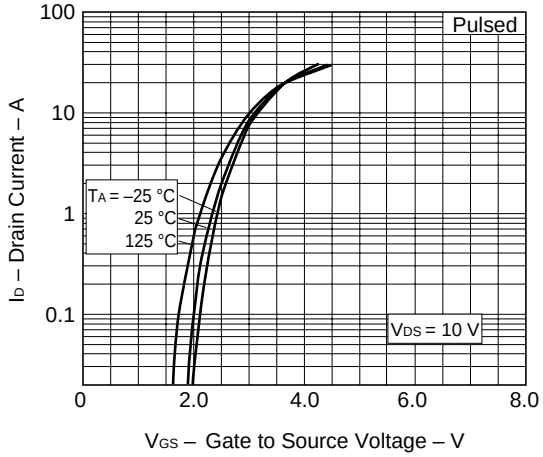
FORWARD BIAS SAFE OPERATING AREA



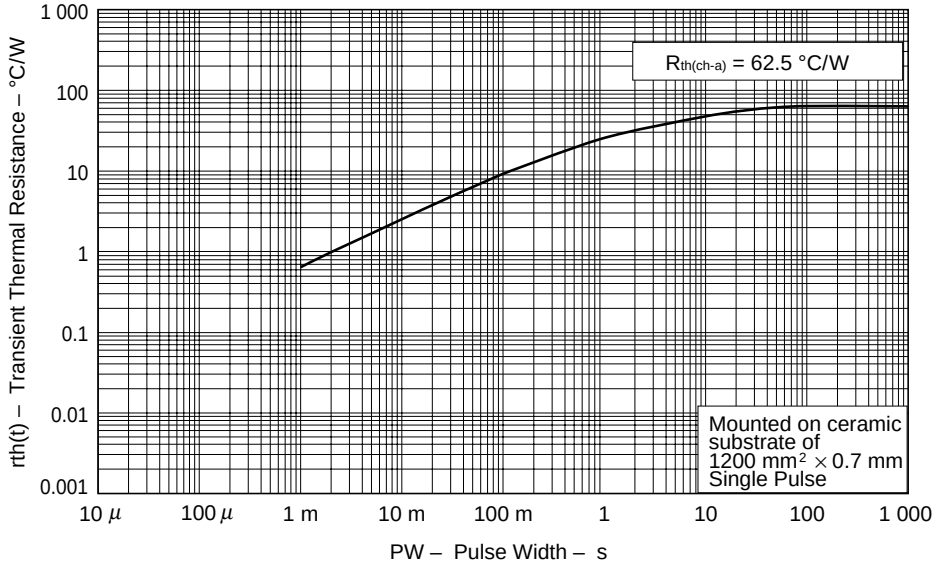
DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE



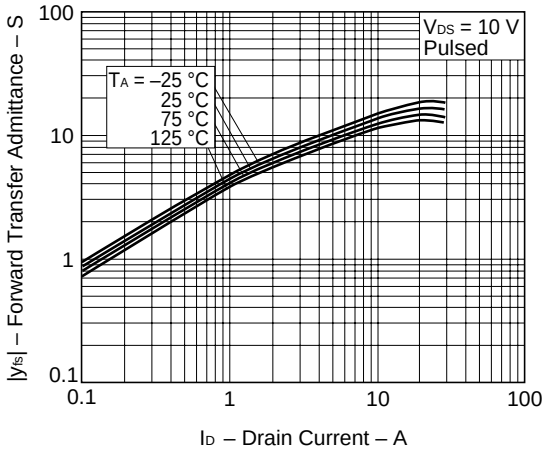
FORWARD TRANSFER CHARACTERISTICS



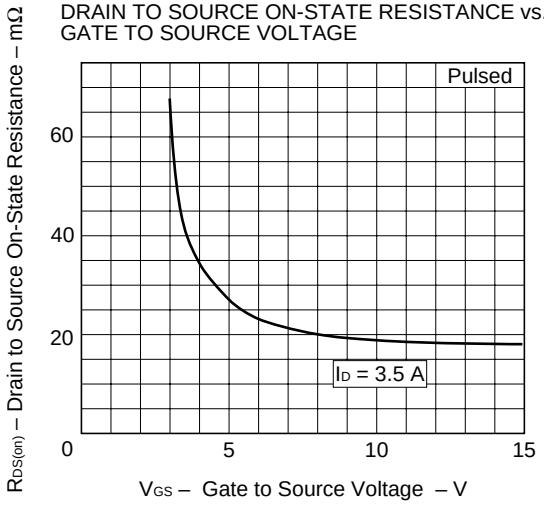
TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH



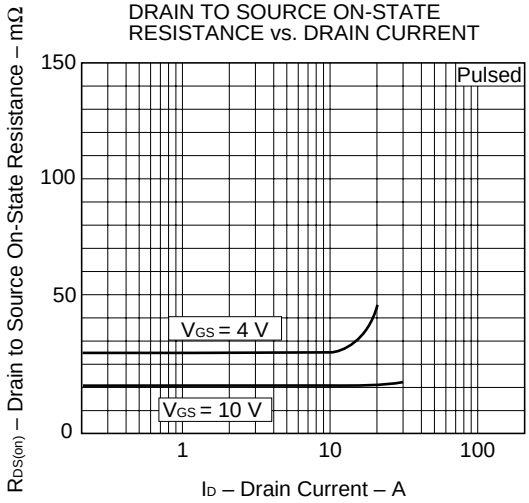
FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT



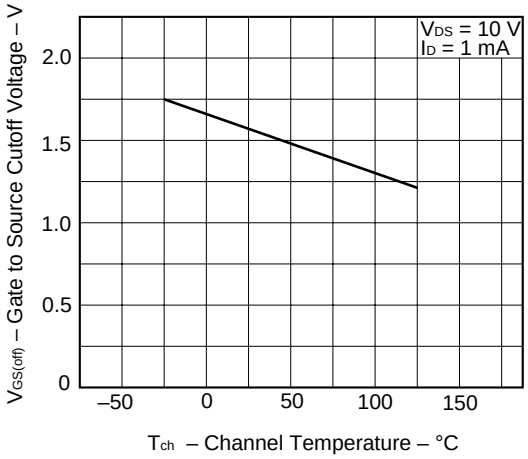
DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE



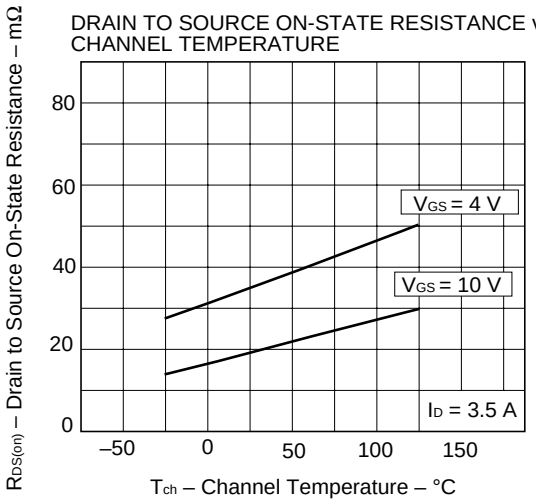
DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT



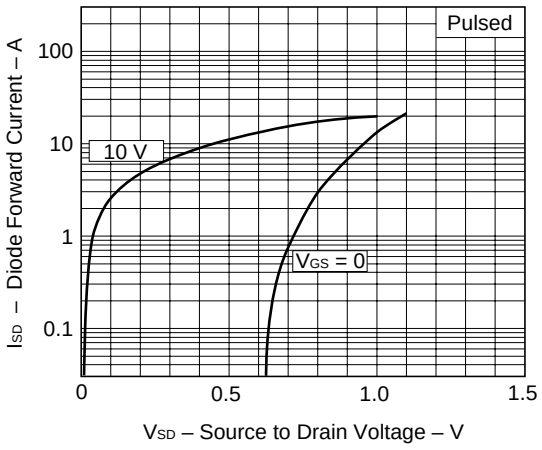
GATE TO SOURCE CUTOFF VOLTAGE vs. CHANNEL TEMPERATURE



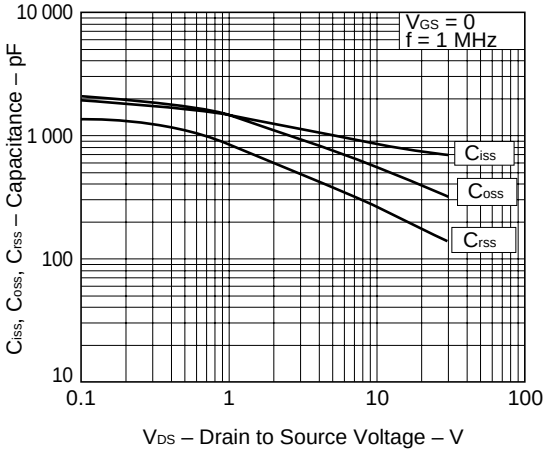
DRAIN TO SOURCE ON-STATE RESISTANCE vs. CHANNEL TEMPERATURE



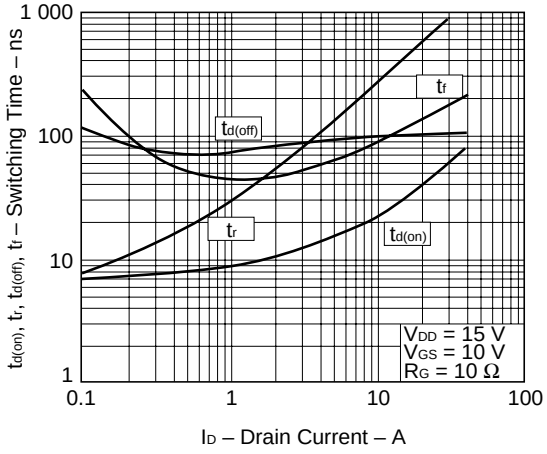
SOURCE TO DRAIN DIODE FORWARD VOLTAGE



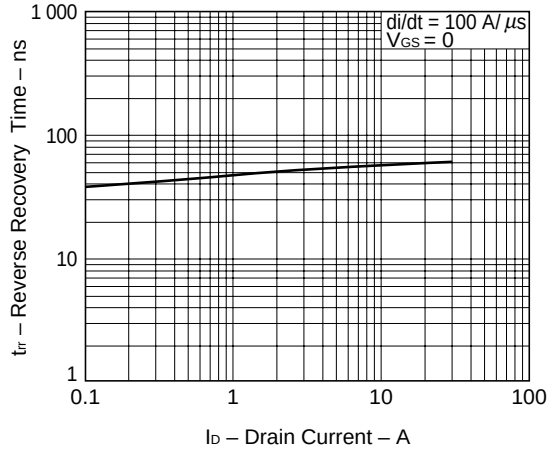
CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE



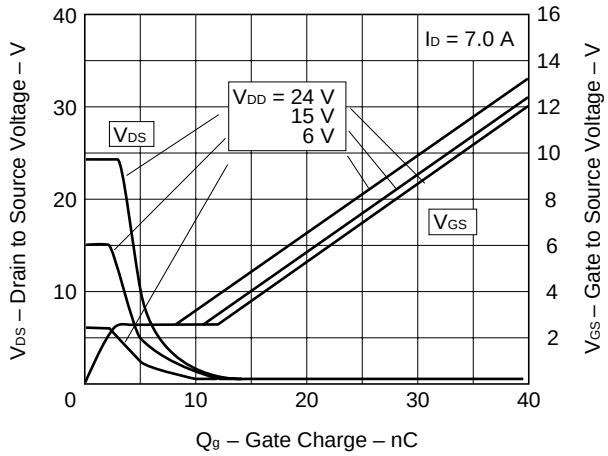
SWITCHING CHARACTERISTICS



REVERSE RECOVERY TIME vs. DRAIN CURRENT



DYNAMIC INPUT/OUTPUT CHARACTERISTICS



REFERENCE

Document Name	Document No.
NEC semiconductor device reliability/quality control system	TEI-1202
Quality grade on NEC semiconductor devices	IEI-1209
Semiconductor device mounting technology manual	IEI-1207
Semiconductor device package manual	IEI-1213
Guide to quality assurance for semiconductor devices	MEI-1202
Semiconductor selection guide	MF-1134
Power MOS FET features and application switching power supply	TEA-1034
Application circuits using Power MOS FET	TEA-1035
Safe operating area of Power MOS FET	TEA-1037

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